

	Type	Hits	Search Text	DBs	Time Stamp
22	BRS	22	silicon adj carbide adj substrate and heat adj treatment same nickel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/19 19:22
23	BRS	49	silicon adj carbide adj substrate and heat adj treatment same metal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/19 19:19
24	BRS	3	silicon adj carbide adj substrate and heat adj treatment same metal and metal with contact adj (hole opening) with (insulating insulation insulated insulator)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/19 19:20
25	BRS	9	silicon adj carbide adj substrate and metal with contact adj (hole opening) with (insulating insulation insulated insulator)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/19 19:21
26	BRS	130	(forming making) near3 silicon adj carbide adj substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/19 19:24
27	BRS	4	(forming making) near3 silicon adj carbide adj substrate and (heated heating heat) with metal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/19 19:23
28	BRS	367	semiconductor adj substrate and silicon adj carbide adj substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/19 19:24
29	BRS	201	semiconductor adj substrate and silicon adj carbide adj substrate and (heat heating heated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/19 19:25

	Type	Hits	Search Text	DBs	Time Stamp
30	BRS	43	semiconductor adj substrate and silicon adj carbide adj substrate and (heat heating heated) with (nickel metal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/19 19:25
31	BRS	11	semiconductor adj substrate and silicon adj carbide adj substrate and (heat heating heated) with (nickel metal) with semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/19 19:26
32	BRS	67	silicon adj carbide with contact adj (hole opening via)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:29
33	BRS	8	silicon adj carbide same contact adj (hole opening via) same nickel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:29
34	BRS	4	"10125620"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:31
35	BRS	14	silicon adj carbide adj substrate and heat adj treatment with nickel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:41
36	BRS	2	jp-08064801-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:45
37	BRS	320	silicon adj carbide and heat adj treatment with nickel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:41

	Type	Hits	Search Text	DBs	Time Stamp
38	BRS	45	(silicon adj carbide SiC) same heat adj treatment with nickel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:46
39	BRS	2	jp-09082663-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:54
40	BRS	234	(silicon adj carbide SiC) with heat with nickel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:46
41	BRS	2	(silicon adj carbide SiC) with heat with nickel and substrate and contact adj (hole via opening)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:47
42	BRS	84	(silicon adj carbide SiC) with heat with nickel and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:16
43	BRS	2	jp-2004076680-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:54
44	BRS	2	jp-2003086534-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 11:54
45	BRS	348	438/931.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:01
46	BRS	67	438/931.ccls. and nickel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:02

	Type	Hits	Search Text	DBs	Time Stamp
47	BRS	19	("4990994" "5124779" "5641975" "5976641").PN. OR ("6110813").URPN.	US-PGPUB; USPAT; USOCR	2006/02/21 14:10
48	BRS	3	(silicon adj carbide SiC) with heat with nickel and substrate and nickel with (etching etch etched)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:17
49	BRS	3	(silicon adj carbide SiC) with heat with nickel and nickel with (etching etch etched)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:17
50	BRS	57	(silicon adj carbide and substrate and metal and heat and (etch etching etched)).clm.	US-PGPUB	2006/02/21 14:23
51	BRS	14	(silicon adj carbide and substrate and metal with heat and (etch etching etched)).clm.	US-PGPUB	2006/02/21 14:22
52	BRS	3	(silicon adj carbide and substrate and metal with heat and (etch etching etched) with metal).clm.	US-PGPUB	2006/02/21 14:23
53	BRS	1	(silicon adj carbide with substrate with metal and heat and (etch etching etched) with metal).clm.	US-PGPUB	2006/02/21 14:23
54	BRS	1	(silicon adj carbide with substrate with metal and heat and (etch etching etched) and nickel).clm.	US-PGPUB	2006/02/21 14:23
55	BRS	8	(silicon adj carbide with substrate with metal and heat and (etch etching etched)).clm.	US-PGPUB	2006/02/21 14:23
56	BRS	175	438/602.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:28

	Type	Hits	Search Text	DBs	Time Stamp
57	BRS	46	438/602.ccls. and silicon adj carbide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:28
58	BRS	17	438/602.ccls. and silicon adj carbide and nickel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:28
59	BRS	1110	257/77.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:27
60	BRS	637	257/77.ccls. and silicon adj carbide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:28
61	BRS	183	257/77.ccls. and silicon adj carbide and nickel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:28
62	BRS	1736	438/796.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:28
63	BRS	24	438/796.ccls. and silicon adj carbide	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:28
64	BRS	10	438/796.ccls. and silicon adj carbide and nickel	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2006/02/21 14:28